IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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APPLICATION SERIAL NO	
FILING DATE	
INVENTORSHIP	Salman Akram et al.
ASSIGNEE	Micron Technology, Inc.
GROUP ART UNIT	
EXAMINER	F. Abraham
ATTORNEY'S DOCKET NO	Ml22-2469
TITLE: Methods of Sensing Temperature of an	Electronic Device Workpiece

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

By:

Citation of the referenced art is respectfully requested.

Dated: 6 9 05

Respectfully submitted,

James D. Shaurette Reg. No. 39,833

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

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ATTY. DOCKET NO. MI22-2469

SERIAL NO. 10/773,383

APPLICANT Salman Akram et al.

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	АА	5,9	964,395	10/12/1999	Glovatsky et al.						
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	AG	5,8	330,372	11/1998	Hierold						(X) "
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APPLICANT Salman Akram et al.

FILING DATE GROUP February 6, 2004 U.S. PATENT DOCUMENTS Class Date Subclass Filing Date *Examiner Document Name If Appropriate Number Initial 4,104,589 8/1/1978 Baker et al. AA ΑB AC ΑD ΑE AF AG AΗ Αl ΑK ΑL AM AN ΑO ΑP AQ FOREIGN PATENT DOCUMENTS OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) AR AS ΑT DATE CONSIDERED **EXAMINER**

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O Inventor:

Salman Akram et al.

Zitle:

Methods of Sensing Temperature of an Electronic Device Workpiece

Assignee:

Micron Technology, Inc.

EL979949672

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 10/042,707, filed May 16, 2002, which is a continuation of U.S. Patent Application Serial No. 09/389,924, filed September 3, 1999, which was a divisional application of U.S. Patent Application Serial No. 09/032,184, filed February 27, 1998. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated:

By:

James D. Shaurette

Reg. No. 39,833

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

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*Examiner Initial Number Date Name Class Subclass

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